

ABSTRACT OF THE DISCLOSURE

A semiconductor chip, a mold resin sealing the semiconductor chip, and a plurality of conductor leads extending from an inside of the mold resin to an outside thereof are provided. A portion of each conductor lead arranged inside the mold resin forms an internal terminal portion, and a portion thereof arranged outside the mold resin forms an external terminal portion. An electrode of the semiconductor chip and the internal terminal portion of the conductor lead are connected. The internal terminal portion of at least one of the conductor leads forms an inductance element portion, at least a part of which is narrower than the external terminal portion. An inductance element formed in a resin package has stable characteristics, and the stability of high-frequency characteristics improves.

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